# Development of metal ion beams and beam transmission at JYFL



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## Content:

- MIVOC method for the production of metal ion beams
- oven development at JYFL
- sputter development at JYFL
- beam transmission efficiency
- beam structure
- beam neutralization (space charge compensation)



JYFL 6.4 GHz ECRIS JYVÄSKYLÄN YLIOPISTO

#### JYFL 14 GHz ECRIS



Main source for the K-130 cyclotron



Back up for cyclotron

lon beam related R&D

![](_page_1_Picture_7.jpeg)

Element	Method	Intensity [µA] (q/mÅ02 )	Note	
В	MIVOC	235	$(C_2H_{12}B_{10})$	IVVÄSKVLÄN VLIOPISTO
С	CO <sub>2</sub>	195		JIVASKILAN ILIOIISIO
F	SF <sub>6</sub>	19	6.4 GHz	Solid ion beams at IYFL
Mg	MIVOC	12	6.4 GHz	
Al	Oven	9.5	6.4 GHz	
Si	SiH <sub>4</sub>	124		Ovens, MIVOC, sputter technique
S	SF <sub>6</sub>	22	6.4 GHz	
Cl	TiCl <sub>4</sub>	23	6.4 GHz	
Ca	Oven	75	CaO + Zr	
Ti	MIVOC	45	CH <sub>3</sub> ) <sub>5</sub> C <sub>5</sub> Ti(CH <sub>3</sub> ) <sub>3</sub>	
V	MIVOC	10	V(C <sub>5</sub> H <sub>5</sub> ) <sub>2</sub>	
Cr	Ind. oven	20		
Mn	Oven	22.5		
Fe	MIVOC	115	Fe(C <sub>5</sub> H <sub>5</sub> ) <sub>2</sub>	
Со	MIVOC	12	Co(C <sub>5</sub> H <sub>5</sub> ) <sub>2</sub>	
Ni	MIVOC	55	Ni(C <sub>5</sub> H <sub>5</sub> ) <sub>2</sub>	
Cu	Oven	7.5		
Zn	Sputter	5.5	6.4 GHz	
Sr	Oven	30	ZrO + Zr	
Y	Foil oven	5		
Zr	Sputter	12		A such as budget the state
Ru	MIVOC	9.1	$Ru(C_5H_5)_2$	
Ag	Oven	5.8	. aret.	
Au	Oven	15		

![](_page_3_Picture_0.jpeg)

# MIVOC method: Metal Ions from VOlatile Compounds

Compound including element of interest and having adequate vapor pressure has to be found!

![](_page_3_Picture_3.jpeg)

![](_page_4_Figure_0.jpeg)

## MIVOC is very effective for some metal ion beams like iron

![](_page_5_Figure_1.jpeg)

 used at RIKEN for studies of superheavy elements

#### Drawbacks:

- lack of suitable compounds

JYVÄSKYLÄN YLIOPISTO

- carbon contamination

FIG. 1. Beam intensity of Fe, Ni, Ru, and Os ions as a function of charge state.

![](_page_5_Picture_7.jpeg)

## JYFL evaporation ovens

![](_page_6_Picture_1.jpeg)

a) Miniature oven, b) foil oven, c) induction oven

Main problem concerning the oven technique:

Surface to surface stability!

TABLE V. Maximum temperatures (°C) for surface-to-surface stability for some ceramics and refractory metals.<sup>a</sup>

	С	w	Mo	Ta	ThO <sub>2</sub>	ZrO2	MgO	BeO
BeO	2300	2000	1900	1600	2100	1900	1800	
MgO	1800	2000	1600	1600	2200	2000		1800
$ZrO_2$	1600	1600	2200	1700	2200		2000	1900
ThO <sub>2</sub>	2000	2200	1900			2200	2200	2100
$Al_2O_3$	1300 <sup>b</sup>	1700 <sup>c</sup>	1800 <sup>c,d</sup>	1700 <sup>e</sup>				
BN	1900°			1500 <sup>e</sup>				
С		$1400^{\circ}$	1200°	1000°				

![](_page_6_Picture_7.jpeg)

## JYFL miniature oven

![](_page_7_Picture_1.jpeg)

![](_page_7_Picture_2.jpeg)

![](_page_8_Figure_0.jpeg)

![](_page_8_Picture_1.jpeg)

![](_page_9_Picture_0.jpeg)

## JYFL inductively heated oven

![](_page_10_Picture_1.jpeg)

#### - home-made control unit

![](_page_10_Figure_3.jpeg)

![](_page_11_Picture_0.jpeg)

# Induction oven at 2000°C

![](_page_11_Picture_2.jpeg)

Reliable tests have been carried out at 1800 - 1900°C at least for a week

Main problem: surface-to-surface reactions between crucible material and material to be evaporated!

![](_page_11_Picture_5.jpeg)

![](_page_12_Picture_0.jpeg)

# Sputter technique

## For ECRIS the method has been developed at ANL

- plasma particles are accelerated by negative voltage (≈ 1 kV)

![](_page_12_Figure_4.jpeg)

![](_page_12_Picture_5.jpeg)

![](_page_13_Picture_0.jpeg)

# Sputter yield

Efficiency of the method depends on the sputter yield of material

Yield = number of removed atoms/number of incident particles INPUT:

![](_page_13_Figure_4.jpeg)

![](_page_14_Picture_0.jpeg)

![](_page_14_Figure_1.jpeg)

![](_page_14_Picture_2.jpeg)

![](_page_15_Figure_0.jpeg)

![](_page_15_Picture_1.jpeg)

- Operation very sensitive on sample position!
- radiation from plasma destroyed the sliding o-ring!
- intensity level of 10 µA with oxygen plasma at 10 kV

![](_page_16_Picture_0.jpeg)

Element	Yield	Element	Yield
Ag	3.4	Ni	1.5
Al	1.2	Os	0.9
Au	2.8	Pd	(2.4)
Be	0.8	Pt	1.6
С	0.2	Re	(0.9)
Co	1.4	Rh	1.5
Cr	1.3	Ru	(1.3)
Cu	2.3	Si	0.5
Fe	1.3	Та	0.6
Ge	1.2	Th	0.7
Hf	0.8	Ti	(0.6)
Ir	1.2	U	1
Mg	1.4	V	0.7
Mn	1.3	W	(0.6)
Mo	(0.9)	Y	0.6
Nb	0.6	Zr	(0.7)

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Table 2: Sputter yields for different elements

- similar results can be anticipated with some other refractory elements using sputter technique!

![](_page_17_Figure_0.jpeg)

## Problem: Asymmetric beam profiles

![](_page_18_Picture_1.jpeg)

#### Beam profiles have been studied by KBr-viewers

![](_page_18_Picture_3.jpeg)

- In 2007 it was found that the beam profile is asymmetric
- Can be due to the wrong entrance/exit angle of DJ1, which would cause different focusing properties in different planes
- will increase 2D-emittance later if solenoid focusing is used

![](_page_18_Picture_7.jpeg)

![](_page_19_Picture_0.jpeg)

## Hollow beam structure

![](_page_19_Picture_2.jpeg)

40 Ar 9+ / ACC 12,14 kV / max intensity at FCJ2 about 110 uA SOLJ1 98 A / SOLJ2 0 A / This is the beam shape with maximum intensity

## More pronounced:

- with low acceleration voltage
- with high intensities
- with high focusing power
- for low charge states

![](_page_19_Picture_9.jpeg)

![](_page_20_Picture_0.jpeg)

# Effect of acceleration voltage

Ar<sup>8+</sup>, 10 kV, 143  $\mu$ A, 277  $\pi$  mmmrad Ar<sup>8+</sup>, 14 kV, 195  $\mu$ A, 186  $\pi$  mmmrad Effect on emittance and intensity bigger than can be explained by the voltage scaling!

![](_page_20_Picture_3.jpeg)

![](_page_20_Picture_4.jpeg)

![](_page_20_Picture_5.jpeg)

![](_page_21_Picture_0.jpeg)

![](_page_21_Figure_1.jpeg)

Effect much bigger than can be anticipated from voltage scaling!

Reason: Less hollow beam?

![](_page_21_Picture_4.jpeg)

## Charge state dependence

![](_page_22_Picture_1.jpeg)

Ar<sup>8+</sup>, 10 kV, erms 277  $\pi$  mmmrad

![](_page_22_Picture_3.jpeg)

Ar<sup>9+</sup>, 10 kV, erms 162  $\pi$  mmmrad

![](_page_22_Picture_5.jpeg)

Location of focal point depends on the charge state: higher charge state can "explode" lower charge state if intensity high enough Indicates (possibly) that hollow beam structure is formed inside the beam line Space charge compensation effect: preliminary unpublished results!

![](_page_23_Picture_1.jpeg)

Gas was fed into the beam line close to the focal points (N<sub>2</sub>, Ar) Ar<sup>8+</sup>, 10 kV, 143  $\mu$ A, 1.8E-7 mbar Ar<sup>8+</sup>, 10 kV, 120  $\mu$ A, 6.2E-6 mbar

![](_page_23_Picture_3.jpeg)

![](_page_23_Picture_4.jpeg)

Clear optimum for brightness is found!

Indicates that hollow beam structure is formed in the beam line

# Frequency tuning

![](_page_24_Picture_1.jpeg)

In the experiment the µw-frequency was changed. Collaboration with LNS ion source group (idea by L. Celona)

Ar<sup>8+</sup>, 14.100 GHz, 91 μA Ar<sup>8+</sup>, 14.125 GHz, 94 μA Klystron + TWTA

![](_page_24_Picture_4.jpeg)

- frequency affects the hollowness of the beam.
- with two frequency heating two rings can be seen in some cases (this cannot be produced by optics)

![](_page_25_Picture_0.jpeg)

# Summary and future plans

- MIVOC method, inductively heated oven and use of sputter technique makes possible the wide variety of metal ion beams
- the beam transport plays an important role concerning the heavy ion facilities
- the hollow beam structure decreases remarkably the transport efficiency
  - experiments have shown that it can be formed:
    - 1) Inside the plasma (frequency tuning)
    - 2) Inside the beam line (voltage and charge state effect, compensation)
  - further studies are needed for better understanding
  - ion beam quality can be improved (even in the case of highly charged ion beams) with residual gas related compensation
  - filament will be tested for beam compensation